

	Type	Hits	Search Text
1	BRS	2077	((semiconductor or wafer or substrate) with carrier with pressure) and (pad)
2	IS&R	67277	("451").CLAS.
3	BRS	1126	S1 and S2
4	IS&R	1043	(451/398).CCLS.
5	BRS	185	S3 and S4
6	IS&R	3675	(451/41).CCLS.
7	IS&R	1	("0000285").PN.
8	IS&R	1	("0000287").PN.
9	IS&R	1171	(451/285).CCLS.
10	IS&R	1308	(451/287).CCLS.
11	BRS	5	("5423716" "5916015" "6080050" "6443824" "6447379").PN.
12	BRS	43	((semiconductor or wafer or substrate) with carrier with pressure) and (pad) and (spring adj constant)
13	BRS	11	((semiconductor or wafer or substrate) with carrier with pressure) and ((pad) with (spring adj constant))
14	BRS	32	S12 not S13
15	IS&R	1424	(451/288).CCLS.

	DBs
1	US-PGPUB; USPAT; EPO; JPO
2	US-PGPUB; USPAT; EPO; JPO
3	US-PGPUB; USPAT; EPO; JPO
4	US-PGPUB; USPAT; EPO; JPO
5	US-PGPUB; USPAT; EPO; JPO
6	US-PGPUB; USPAT; EPO; JPO
7	US-PGPUB; USPAT; EPO; JPO
8	US-PGPUB; USPAT; EPO; JPO
9	US-PGPUB; USPAT; EPO; JPO
10	US-PGPUB; USPAT; EPO; JPO
11	US-PGPUB; USPAT; EPO; JPO
12	US-PGPUB; USPAT; EPO; JPO
13	US-PGPUB; USPAT; EPO; JPO
14	US-PGPUB; USPAT; EPO; JPO
15	US-PGPUB; USPAT; EPO; JPO